

ABSTRACT OF THE DISCLOSURE

A ball electrode forming method comprises steps of: preparing a semiconductor apparatus having a plurality of electrode pads; arranging a mask
5 having an upper surface and a lower surface, an area in the lower surface being larger than an area in the upper surface, and a plurality of openings extended from the upper surface to the lower surface, on a surface of the semiconductor apparatus having the electrode pads formed thereon so that the surface and the lower surface can face each other; arranging solder balls on the electrode pads
10 arranged in the openings from the upper surface side of the mask; and electrically connecting the solder balls to the electrode pads to form ball electrodes. Thus, regarding a method for forming a ball electrode in a semiconductor apparatus having a BGA structure, an efficient ball electrode forming method is employed to prevent omission of a ball electrode.

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